

Title (en)
COPPER-NICKEL-ZINC ALLOY CONTAINING SILICON

Title (de)
SILIZIUMHALTIGE KUPFER-NICKEL-ZINK-LEGIERUNG

Title (fr)
ALLIAGE DE CUIVRE-NICKEL-ZINC CONTENANT DU SILICIUM

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Application
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Abstract (en)
[origin: WO2013131604A2] The invention includes a copper-nickel-zinc alloy with the following composition in weight %: Cu 47.0 to 49.0%, Ni 8.0 to 10.0%, Mn 0.2 to 0.6%, Si 0.05 to 0.4%, Pb 1.0 to 1.5%, Fe and/or Co up to 0.8%, the rest being Zn and unavoidable impurities, wherein the total of the Fe content and double the Co content is at least 0.1 weight % and wherein mixing silicides containing nickel, iron and manganese and/or containing nickel, cobalt and manganese are stored as spherical or ellipsoidal particles in a structure consisting of an alpha- and beta-phase. The invention further relates to a method for producing semi-finished products from a copper-nickel-zinc alloy.

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